comprising various scribe line widths.

the first direction.

10. The scribe lines of claim 9 wherein the second direction is perpendicular to

[c10]

| | [c11] | 11. The scribe lines of claim 1 wherein the dies are in the same shapes and sizes. |
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| and the state of t | [c12] | 12. The scribe lines of claim 1 wherein the dies comprise various die shapes. |
| | [c13] | 13. The scribe lines of claim 1 wherein the dies comprise various die sizes. |
| | [c14] | 14. Scribe lines on a wafer, the wafer comprising a plurality of dies, the scribe lines comprising: a plurality of first scribe lines positioned in gaps of the dies, each of the first scribe lines comprising a predetermined pattern; and |
| | | a plurality of second scribe lines positioned in gaps of the dies, the second scribe lines being narrower than the first scribe lines. |
| | [c15] | 15.The scribe lines of claim 14 wherein the predetermined pattern comprises an alignment mark for aligning elements on different dies. |
| | [c16] | 16. The scribe lines of claim 14 wherein the predetermined pattern comprises a test key for performing a quality test on the dies. |
| | [c17] | 17.The scribe lines of claim 14 wherein the first scribe lines comprise at least an arranging direction. |
| | [c18] | 18.The scribe lines of claim 14 wherein the second scribe lines comprise at least an arranging direction. |
| | [c19] | 19/The scribe lines of claim 14 wherein the dies are in the same shapes and sizes. |
| | [c20] | 20. The scribe lines of claim 14 wherein the dies comprise various die shapes. |
| | [c21] | 21.The scribe lines of claim 1 wherein the dies comprise various die sizes. |